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Of interest to editors and journalists covering:  
Electronics, Semiconductors, Silicon Valley and CA Business

#### IPAC Announces High-Volume QFN Production Onshore

SAN JOSE, Calif. - Nov. 14, 2003 /Send2Press Newswire/ -- Integrated Packaging Assembly Corporation ("IPAC" - [www.ipac.com](http://www.ipac.com)), an IC packaging foundry in Silicon Valley, announced that they are the only US source for high-volume QFN (Quad-Flat package, No-lead) package assembly. With ample available capacity at their conveniently located, ISO-9002 certified San Jose facility, the company turns all production orders in less than one week door-to-door and can accommodate urgent lots as quickly as 24 hours. Related services including testing and wafer thinning are also offered as a turnkey solution.

"QFN-type packaging is rapidly becoming the IC package used for most chips with less than 100 I/Os," said Chris Ooi, IPAC's executive VP. "The near-chip-scale leadframe based platform offers numerous and significant advantages over other IC package types," he points out. "These improvements include low cost, small footprint, high reliability, high thermal and electrical performance, and low tooling and manufacturing costs. These features make QFN and related outlines suitable for a huge range of IC products including RF, analog, mixed signal and logic, especially those used in portable and wireless applications."

With QFN packaging, IPAC is the domestic packaging foundry with by far the most package types available. The company's production capabilities include QFP, QFN, BGA, FBGA, Flip-Chip and SiP. Advanced wafer-level and system-level packaging solutions are also under development and planned for introduction in 2004.

IPAC provides IC package assembly, testing and manufacturing support to the semiconductor industry. The company's manufacturing services are carried out at its Silicon Valley facility where a wide range of package offerings are combined with superior service and fast delivery. For more information, visit IPAC's web site at: <http://www.ipac.com>.

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